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PARTICULATE OR PARTICLE-BOUND CHELATING AGENTS

ABSTRACT

The invention generally relates to compositions and methods for chemically mechanically polishing a substrate, including a polishing accelerator, which is normally one
5 or more oxidizers, an abrasive material, and chelating particles and/or metal-absorbent clay material. In addition, the invention can also involve methods of forming chelator particles and methods of separating metal-containing ions from polishing and/or etching solutions after polishing and/or etching.